

Solids and Semi-conductor Devices

Solids

It is a state of matter which has a definite shape and a definite volume. The characteristic properties of the solid depends upon the nature of forces acting between their constituent particles (*i.e.* ions, atoms or molecules). Solids are divided into two categories.

| Crystalline solids | Amorphous or glassy solids |
|---|---|
| (1) These solids have definite external geometrical form. | These solids have no definite external geometrical form. |
| (2) Ions, atoms or molecules of these solid are arranged in a definite fashion in all it's three dimensions. $\qquad \qquad \qquad$ | Ions, atoms or molecules of these solids are not arranged in a definite fashion. $\int \int \int$ |
| (3) Examples : Quartz, calacite, mica, diamond etc. | Example : Rubber, plastic, paraffin wax, cement <i>etc</i> . |
| (4) They have well defined facets or faces. | They do not possess definite facets or faces. |
| (5) They are ordered at short range as well as at long range. | These may be short range order, but there is no long range order. |
| (6) They are anisotropic, <i>i.e.</i> the physical properties like elastic modulii, thermal conductivity, electrical conductivity, refractive index have different values in different direction. | They are isotropic <i>i.e.</i> physical properties are similar in all direction. |
| (7) They have sharp melting point. | They may not have a sharp melting point. |
| (8) Bond strengths are identical throughout the | Bond strengths vary. |

| solid. | |
|---|--|
| (9) These are considered as true solids. | These are considered as pseudo-solids or super cooled liquids. |
| (10) An important property of crystals is their symmetry. | Amorphous solids do not have any symmetry. |

Terms Related With Crystal Structure

(1) Crystal lattice

It is a geometrical arrangement of points in space where if atoms or molecules of a solid are placed, we obtain an actual crystal structure of the solid.

Crystal

Basis

Lattic

(2) Basis

The atoms or molecules attached with every lattice point in a crystal structure is called the basis of crystal structure. Thus,



Is defined as that volume of the solid from which the entire crystal structure can be constructed by the translational repetition in three dimensions. The length of three sides of a unit cell (3*D*) are called primitives or lattice constant they are denoted by a, b, c



(4) Primitive cell

A primitive cell is a minimum volume unit cell or the simple unit cell with particles only at the corners is a primitive unit cell and other types of unit cells are called non-primitive unit cells. There is only one lattice point per primitive cell.

(5) Crystallographic axis

The lines drawn parallel to the lines of intersection of the faces of the unit cell are called crystallographic axis.

Note : The location of each atom or molecule in a crystal lattice may be marked as a point which is called lattice point.

All the crystals on the basis of the shape of their unit cells, have been divided into seven crystal systems as shown in the following table.

| S. No. | System | No. of lattice | Lattice constant | Angle between lattice constants | Examples |
|-----------|----------------------------------|-------------------|---------------------|---|---|
| | | S | S | | |
| (i) | Cubic | 3 | a = b = c | $\alpha = \beta = \gamma = 90^{\circ}$ | Diamond, NaCl, Li, Ag, Cu, NH_4Cl , Pb etc. |
| (ii) | Tetragonal | 2 | $a = b \neq c$ | $\alpha = \beta = \gamma = 90^{\circ}$ | White tin, <i>NiSO</i> ₄ etc. |
| (iii) | Orthorhombi | 4 | $a \neq b \neq c$ | $\alpha = \beta = \gamma = 90^{\circ}$ | <i>HgCl</i> ₂ , <i>KNO</i> ₃ , gallium <i>etc</i> . |
| | с | | | | |
| (iv) | Monoclinic | 2 | $a \neq b \neq c$ | $\alpha = \gamma = 90^{\circ} \text{ and } \beta \neq 90^{\circ}$ | KclO ₃ , FeSO ₄ etc. |
| (v) | Triclinic | 1 | $a \neq b \neq c$ | $\alpha \neq \beta \neq \gamma \neq 90^{\circ}$ | $K_2Cr_2O_7$, $CuSO_4$ etc. |
| (vi) | Rhombo- hedral or Trigonal | 1 | a = b = c | $\alpha = \beta = \gamma \neq 90^{\circ}$ | Calcite, As, Sb, Bi etc. |
| (vii) | Hexagonal | 1 | $a = b \neq c$ | $\alpha = \beta = 90^{\circ} \text{ and } \gamma = 120^{\circ}$ | Zn, Cd, Ni etc. |

Cubic Lattices

(1) Different symmetry

(i) **Centre of symmetry :** An imaginary point within the crystal that any line drawn through it intersects the surface of the crystal at equal distances in both directions.



(ii) **Plane of symmetry :** It is an imaginary plane which passes through the centre of a crystal and divides it into two equal portions such that one part is exactly the mirror image of the other.



(iii) **Axis of symmetry** : It is an imaginary straight line about which, if the crystal is rotated, it will present the same appearance more than once during the complete revolution.

In general, if the same appearance of a crystal is repeated on rotating through an angle $\frac{360^{\circ}}{n}$, around an imaginary axis, the axis is called an *n*-fold axis.



A cubical crystal possesses in all 13 axis of symmetry.

(iv) **Elements of symmetry :** The total number of planes, axes and centre of symmetry possessed by a crystal are termed as elements of symmetry. A cubic crystal possesses a total of 23 elements of symmetry.

Planes of symmetry = (3 + 6) = 9, Axes of symmetry = (3 + 4 + 6) = 13, Centre of symmetry = 1. Total number of symmetry elements = 23

(2) Different lattice in cubic crystals



(3) Atomic radius

The half of the distance between two atoms in contact is defined as atomic radius.



(4) Atoms per unit cell

An atom located at the corner of a unit cell of a lattice is shared equally by eight other unit cells in the three dimensional lattice. Therefore, each unit cell has $1/8^{\text{th}}$ share of an atom at its each corner. Similarly, a face of the unit cell is common to the two unit cells in the lattice. Therefore, each unit cell has 1/2 share of an atom at its each face. The atom located at the centre of the unit cell belongs completely to the unit cell.

Let N_c , N_b and N_f be the number of atoms at the corners, centre and face of the unit cell respectively. Therefore the number of atoms per unit cell is given by $N = N_b + \frac{N_f}{2} + \frac{N_c}{8}$

(i) In sc lattice : $N_b = 0$, $N_f = 0$, $N_c = 8$ so N = 1

(ii) In *bcc* lattice : $N_{b} = 1$, $N_{f} = 0$, $N_{c} = 8$ so N = 2

(iii) In fcc lattice : $N_b = 0$, $N_f = 6$, $N_c = 8$ so N = 4

(5) Co-ordination number

It is defined as the number of nearest neighbours that an atom has in a unit cell. It depends upon structure.

(i) Simple cubic structure : Each atom has two neighbours along *X*-axis, two along *Y*-axis and two along *Z*-axis so coordination number = 6.

(ii) Face-centred cubic structure: Every corner atom has four neighbours in each of the three planes *XY*, *YZ*, and *ZX* so coordination number = 12

(iii) Body-centred cubic structure: The atom of the body of the cell has eight neighbours at eight corner of the unit cell so coordination number = 8.

(6) Atomic packing fraction (or packing factor or relative packing density)

The atomic packing fraction indicates how close the atoms are packed together in the given crystal structure or the ratio of the volume occupied by atoms in a unit cell in a crystal and the volume of unit cell is defined as APF.

(i) **For sc crystal :** Volume occupied by the atom in the unit cell $=\frac{4}{3}\pi r^3 = \frac{\pi a^3}{6}$. Volume of the

unit cell = a^3

Thus P.F. =
$$\frac{\pi a^3 / 6}{a^3} = \frac{\pi}{6} = 0.52 = 52\%$$

(ii) For bcc : P.F. = $\frac{\sqrt{3}\pi}{8} = 68\%$ (iii) For fcc : P.F. = $\frac{\pi}{3\sqrt{2}} = 74\%$

(7) Density of unit cell

Density of unit cell = $\frac{\text{Mass of the unit cell}}{\text{Volume of the unit cell}} = \frac{nA}{NV} = \frac{nA}{Na^3}$

where n = Number of atoms in unit cell (For *sc* lattice n = 1, for *bcc* lattice n = 2, for *fcc* lattice n = 4), A = atomic weight, N = Avogadro's number, V = Volume of the unit cell.

(8) Bond length

The distance between two nearest atoms in a unit cell of a crystal is defined as bond length.

(i) In a *sc* lattice : Bond length = *a* (ii) In a *bcc* lattice : Bond length = $\frac{\sqrt{3}a}{2}$ (iii) In a *fcc* lattice :

Bond length
$$=\frac{a}{\sqrt{2}}$$

Note : 🗆 Hexagonal closed packed (HCP) lattice –

$$\Rightarrow a = b \neq a$$

 \Rightarrow Coordination number = 12

$$\Rightarrow$$
 P.F. $=\frac{\pi\sqrt{2}}{6}$

 \Rightarrow Number of atoms per unit cell = 2

 \Rightarrow Magnesium is a special example of HCP lattice structure.

Types of Binding and Crystals

(1) **Binding :** Bindings among the atoms or molecules are mainly of following types.

| S. No. | Binding | Cause of binding | M.P. | Electrical conductivit y | Examples |
|-----------|----------------|--|--------------|--------------------------------|---|
| (i) | Ionic | Electrostatic force between positive and negative ions | Very high | Very low | <i>NaCl, CsCl, LiF</i> etc. |
| (ii) | Covalent | Sharing of electrons of opposite spins between two neutral atoms | High | Semi conductor | <i>Ge, Si,</i> diamond etc. |
| (iii) | Hydrogen | Mutual electrostatic interaction between molecules of surface of different electron densities | Low | Insulator | H_2O |
| (iv) | Vander Waal | Non polar molecules or Vander Waal forces or | Low | Normally insulator | <i>HF</i> , <i>NH</i> ₃ etc. |
| | | dipole-dipole interaction | | | |
| (v) | Metallic | Mutual interaction between electrons and ion lattice | _ | High | Cl_2, I_2, CO_2 etc. |

(2) Three kinds of crystals

(i) **Single crystal :** The crystals in which the periodicity of the pattern extends throughout the piece of the crystal are known as single crystals. Single crystals have anisotropic behaviour *i.e.* their physical properties (like mechanical strength, refractive index, thermal and electrical conductivity) are different along different directions. The small sized single crystals are called mono-crystals.

(ii) **Poly-crystals :** A poly-crystal is the aggregate of the monocrystals whose well developed faces are joined together so that it has isotropic properties. Ceramics are the important illustrations of the poly-crystalline solids.

(iii) **Liquid crystals :** The organic crystalline solid which on heating, to a certain temperature range becomes fluid like but its molecules remain oriented in a particular directions, showing that they retain their anisotropic properties, is called liquid crystal. These crystals are used in a liquid crystal displays (L.C.D.) which are commonly used in electronic watches, clocks and micro-calculators *etc*.

Energy Bands

In isolated atom the valence electrons can exist only in one of the allowed orbitals each of a sharply defined energy called energy levels. But when two atoms are brought nearer to each other, there are alterations in energy levels and they spread in the form of bands.

Energy bands are of following types

(1) Valence band

The energy band formed by a series of energy levels containing valence electrons is known as valence band. At 0 K, the electrons fills the energy levels in valence band starting from lowest one.

(i) This band is always fulfill by electron.

(ii) This is the band of maximum energy.

(iii) Electrons are not capable of gaining energy from external electric field.

(iv) No flow of current due to such electrons.

(v) The highest energy level which can be occupied by an electron in valence band at 0 *K* is called fermi level.

(2) Conduction band

The higher energy level band is called the conduction band.

(i) It is also called empty band of minimum energy.

(ii) This band is partially filled by the electrons.

(iii) In this band the electrons can gain energy from external electric field.

(iv) The electrons in the conduction band are called the free electrons. They are able to move any where within the volume of the solid.

(v) Current flows due to such electrons.

(3) Forbidden energy gap (ΔE_g)

Energy gap between conduction band and valence band $\Delta E_g = (C.B.)_{\min} - (\sqrt[4]{B.})_{\max}$

(i) No free electron present in forbidden energy gap.

(ii) Width of forbidden energy gap upon the nature of substance.

(iii) As temperature increases (\uparrow), forbidden energy gap decreases (\downarrow) very signity. ^{min}

C.B. max ΔE_g max V.B. max SUBDIN.

Types of Solids

On the basis of band structure of crystals, solids are divided in three categories.

| S.No. | Properties | Conductors | Insulators | Semiconductors | |
|-------|--|---|--|---|--|
| (1) | Electrical conductivity | 10² to 10 ⁸ U/m | 10 ⁻⁸ Ŭ/m | 10 ⁻⁵ to 10° V/m | |
| (2) | Resistivity | 10 ⁻² to 10 ⁻⁸ Ω-m (negligible) | 10 ⁸ Ω-m | 10 ⁵ to 10 ⁰ Ω-m | |
| (3) | Band structure | C.B. V.B. | $C.B.$ \uparrow ΔE_g \downarrow $V.B.$ | C.B. ΔE_g \mathbf{V} .B. | |
| (4) | Energy gap | Zero or very small | Very large; for diamond it is 6 <i>eV</i> | For $Ge E_g = 0.7 eV$ for $Si E_g = 1.1 eV$ | |
| (5) | Current carries | Free electrons | | Free electrons and holes | |
| (6) | Condition of V.B. and C.B. at ordinary temperature | V.B. and C.B. are completely filled or C.B. is some what empty | V.B. – completely filled C.B. – completely unfilled | V.B. – somewhat empty C.B. – somewhat filled | |
| (7) | Temperature co- efficient of resistance (α) | Positive | Zero | Negative | |
| (8) | Effect of temperature on conductivity | Decreases | - | Increases | |
| (9) | Effect of temperature on resistance | Increases | - | Decreases | |
| (11) | Examples | Cu, Ag, Au, Na, Pt, Hg etc. | Wood, plastic, mica, diamond, glass etc. | Ge, Si, Ga, As etc. | |
| (12) | Electron density | $10^{29}/m^3$ | _ | $Ge \sim 10^{19} / m^3$ $Si \sim 10^{16} / m^3$ | |

Holes in semiconductors

At absolute zero temperature (O K) conduction band of semiconductor is completely empty and the semiconductor behaves as an insulator.

When temperature increases the valence electrons acquires thermal energy to jump to the conduction band (Due to the braking of covalent bond). If they jumps to C.B. they leaves behind the deficiency of electrons in the valence band. This deficiency of electron is known as *hole* or cotter. A hole is considered as a seat of positive charge, having magnitude of charge equal to that of an electron.

(1) Holes acts as virtual charge, although there is no physical charge on it.

(2) Effective mass of hole is more than electron.

(3) Mobility of hole is less than electron.

Types of Semiconductors

(1) Intrinsic semiconductor

A pure semiconductor is called intrinsic semiconductor. It has thermally generated current carriers

(i) They have four electrons in the outermost orbit of atom and atoms are held together by covalent bond

(ii) Free electrons and holes both are charge carriers and n_e (in C.B.) = n_h (in V.B.)

(iii) The drift velocity of electrons (v_e) is greater than that of holes (v_h)

(iv) For them fermi energy level lies at the centre of the C.B. and V.B.

(v) In pure semiconductor, impurity must be less than 1 in 10^8 parts of semiconductor.

(vi) In intrinsic semiconductor $n_e^{(o)} = n_h^{(o)} = n_i = AT^{3/2}e^{-\Delta E_g/2KT}$; where $n_e^{(o)} =$ Electron density in conduction band, $n_h^{(o)} =$ Hole density in V.B., $n_i =$ Density of intrinsic carriers.

(vii) Because of less number of charge carriers at room temperature, intrinsic semiconductors have low conductivity so they have no practical use.

Net current and conductivity

When some potential difference is applied across a piece of intrinsic semiconductor current flows in it due to both electron and holes *i.e.* $i = i_e + i_h \Rightarrow i = n_e eAv_e$ $i = \epsilon$

Hence conductivity of semiconductor $\sigma = e[n_e \mu_e + n_h \mu_h]$

where v_e = drift velocity of electron, v_h = drift velocity of holes,

E = Applied electric field $\mu_e = \frac{v_e}{E}$ = mobility of e^- and $\mu_n = \frac{v_h}{E}$ = mobility

Note: \Box $(ni)_{Ge} \simeq 2.4 \times 10^{19} / m^3$ and $(ni)_{Si} \simeq 1.5 \times 10^{16} / m^3$

 \Box At room temperature $\sigma_{Ge} > \sigma_{Si}$

- $\Box \quad \mu_e > \mu_h$
- □ Conductivity of semiconductor increases with temperature because number density of charge carriers increases.
- □ In a doped semiconductor, the number density of electrons and holes is not equal. But it can be established that $n_e n_h = n_i^2$; where n_e , n_h are the number density of electrons and holes respectively and n_i is the number density of intrinsic curries



(*i.e.* electrons or holes) in a pure semiconductor. This product is independent of donor and acceptor impurity doping.

(2) Extrinsic semiconductor

- (i) It is also called impure semiconductor.
- (ii) The process of adding impurity is called Doping.
- (iii) Impurities are of two types :



| Pentavalent impurity | Trivalent impurity |
|---|--|
| The elements whose atom has five valance | The elements whose each atom has three |
| impurities e.g. As, P, Sb etc. These are also | valance electrons are called trivalent |
| called donor impurities. These impurities are | impurities e.g. In, Ga, Al, B, etc. These |
| also called donor impurities because they | impurities are also called acceptor impurities |
| donates extra free electron. | as they accept electron. |
| | |

(iv) The number of atoms of impurity element is about 1 in 10^8 atoms of the semiconductor. (v) $n_e \neq n_h$

(vi) In these fermi level shifts towards valence or conduction energy bands.

(vii) Their conductivity is high and they are practically used.

(3) Types of extrinsic semiconductor

| N-type semiconductor | P-type semiconductor |
|--|--|
| (i) Intrinsic S.C. + Pentavale nt | Intrinsic S.C. + Trivalent impurity |
| $ \begin{array}{c} $ | $ \begin{array}{c} $ |
| (ii) Majority charge carriers – electrons | Majority charge carriers – holes |
| Minority charge carriers – holes | Minority charge carriers – electrons |
| (iii) $n_e \gg n_h$; $i_e \gg i_h$ | $n_h >> n_e; i_h >> i_e$ |
| (iv) Conductivity $\sigma \approx n_e \ \mu_e \ e$ | Conductivity $\sigma \approx n_h \mu_h e$ |
| (iv) <i>N</i> -type semiconductor is electrically neutral (not negatively charged) | <i>P</i> -type semiconductor is also electrically neutral (not positively charged) |
| (v) Impurity is called Donar impurity because one impurity atom generate one e^- . | Impurity is called Acceptor impurity. |

| (vi) Donor energy level lies just below the conduction band. C.B. Donor energy | Acceptor energy level lies just above the valence band. |
|--|---|
| V.B. | V.B. |

P-N Junction Diode

When a *P*-type semiconductor is suitably joined to an *N*-type semiconductor, then resulting arrangement is called *P*-*N* junction or *P*-*N* junction diode



(1) **Depletion region**

On account of difference in concentration of charge carrier in the two sections of P-N junction, the electrons from N-region diffuse through the junction into P-region and the hole from P region diffuse into N-region.

Due to diffusion, neutrality of both N and P-type semiconductor is disturbed, a layer of negative charged ions appear near the junction in the P-crystal and a layer of positive ions appears near the junction in N-crystal. This layer is called depletion layer

(i) The thickness of depletion layer is 1 micron = 10^{-6} m.

(ii) Width of depletion layer $\propto \frac{1}{\text{Dopping}}$

(iii) Depletion is directly proportional to temperature.

(iv) The P-N junction diode is equivalent to capacitor in which the depletion layer acts as a dielectric.

(2) Potential barrier

The potential difference created across the P-N junction due to the diffusion of electron and holes is called potential barrier.

For $Ge = V_B = 0.3V$ and for silicon $V_B = 0.7V$

On the average the potential barrier in *P-N* junction is ~ 0.5 *V* and the width of depletion region ~ 10^{-6} .





(3) Diffusion and drift current

Because of concentration difference holes/electron try to diffuse from their side to other side. Only these holes/electrons crosses the junction, having high kinetic energy. This diffusion results is an electric current from the *P*-side to the *N*-side known as diffusion current (i_{df})

As electron hole pair (because of thermal collisions) are continuously created in the depletion region. These is a regular flow of electrons towards the *N*-side and of holes towards the *P*-side. This makes a current from the *N*-side to the *P*-side. This current is called the drift current (i_{dr}).

Note : \Box In steady state $i_{df} = i_{dr}$ so $i_{net} = 0$

□ When no external source is connected, diode is called unbiased.

(4) Biasing

Means the way of connecting *emf* source to *P*-*N* junction diode

| Forward biasing | Reverse biasing | | | | |
|---|---|--|--|--|--|
| (i) Positive terminal of the battery is connected to the <i>P</i> -crystal and negative terminal of the battery is connected to <i>N</i> - crystal $\xrightarrow{F_b} \xleftarrow{F_b} F_b$ | (i) Positive terminal of the battery is connected to the <i>N</i> -crystal and negative terminal of the battery is connected to <i>P</i> - crystal $\xrightarrow{-1}_{E_b} \xleftarrow{E_b} \xleftarrow{e_{\oplus}} \bigcirc \bigcirc \oplus \oplus \bigoplus \bigoplus$ | | | | |
| (ii) Width of depletion layer decreases | (ii) Width of depletion layer increases | | | | |
| (iii) $R_{\rm Forward} \approx 10\Omega - 25\Omega$ | (iii) $R_{\text{Reverse}} \approx 10^5 \Omega$ | | | | |
| (iv) Forward bias opposes the potential barrier and for $V > V_P$ a forward current is set | (iv) Reverse bias supports the potential barrier and no current flows across the | | | | |

| up across the junction. | junction due to the diffusion of the majority carriers. |
|--|--|
| | (A very small reverse currents may exist in the circuit due to the drifting of minority carriers across the junction) |
| (v) Cut-in (Knee) voltage : The voltage at which the current starts to increase. For <i>Ge</i> it is $0.3 V$ and for <i>Si</i> it is $0.7 V$. | (v) Break down voltage : Reverse voltage at which break down of semiconductor occurs.For <i>Ge</i> it is 25 <i>V</i> and for <i>Si</i> it is 35 <i>V</i>. |
| (vi) $df - diffusion$ dr - drift P N G I_{dr} I_{dr} I_{dr} I_{dr} I_{dr} I_{dr} I_{dr} I_{dr} I_{dr} | (vi) $ext{Break}$ Reverse current down $ext{down}$ $ext{Reverse current}$ $ext{down}$ $far identified in the second s$ |

Reverse Breakdown and Special Purpose Diodes

(1) Zener breakdown

When reverse bias is increased the electric field at the junction also increases. At some stage the electric field becomes so high that it breaks the covalent bonds creating electron, hole pairs. Thus a large number of carriers are generated. This causes a large current to flow. This mechanism is known as **Zener breakdown**.

(2) Avalanche breakdown

At high reverse voltage, due to high electric field, the miniority charge carriers, while crossing the junction acquires very high velocities. These by collision breaks down the covalent bonds, generating more carriers. A chain reaction is established, giving rise to high current. This mechanism is called **avalanche breakdown**.

(3) Special purpose diodes

| Zener diode | Light emitting | Photo diode | Solar cells | | |
|---------------------------------|------------------------|------------------------|------------------------------------|--|--|
| | diode (LED) | | | | |
| | 77- | , Lb | It is based on the | | |
| | | | photovoltaic effect. | | |
| | | | One of the | | |
| It is a highly doped <i>p</i> - | Specially designed | In these diodes | semiconductor region | | |
| <i>n</i> junction which is | diodes, which give out | electron and hole | is made so thin that | | |
| not damaged by high | light radiations when | pairs are created by | the light incident on | | |
| reverse current. The | forward biases. LED'S | junction photoelectric | it reaches the <i>p</i> - <i>n</i> | | |
| breakdown voltage is | are made of GaAsp, | effect. That is the | junction and gets | | |
| made very sharp. In | Gap etc. | covalent bonds are | absorbed. It converts | | |

| the forward bias, the | broke | en | by | the | EM | solar | energy | into |
|------------------------|-------|------|--------|------|-------|---------|------------|------|
| zener diode acts as | radia | tio | ns | abso | orbed | electri | cal energy | • |
| ordinary diode. It can | by th | ne e | electr | on i | n the | | | |
| be used as voltage | V.B. | Th | ese | are | used | | | |
| regulator | for | de | tecti | ng | light | | | |
| | signa | ıls. | | | | | | |

P-N Junction Diode as a Rectifier



Transistor

A junction transistor is formed by sandwiching a thin layer of P-type semiconductor between two N-type semiconductors or by sandwiching a thin layer of n-type semiconductor between two P-type semiconductor.



Note : In normal operation base-emitter is forward biased and collector base junction is reverse biased.

(1) **Working of Transistor :** In both transistor emitter - base junction is forward biased and collector – base junction is reverse biased.



<u>Note</u>: □ In a transistor circuit the reverse bias is high as compared to the forward bias. So that it may exert a large attractive force on the charge carriers to enter the collector region.

(2) **Characteristics of transistors :** A transistor can be connected in a circuit in the following three different configurations.

(i) Common base (CB) (ii) Common emitter (CE)(iii) Common collector (CC)

(i) CB characteristics : The graphs between voltages and currents when base of a transistor is common to input and output circuits are known as CB characteristic of a transistor.



(ii) CE characteristics : The graphs between voltages and currents when emitter of a transistor is common to input and output circuits are known as CE characteristics of a transistor.



(3) **Transistor as an amplifier :** A device which increases the amplitude of the input signal is called amplifier.



The transistor can be used as an amplifier in the following three configuration

(i) CB amplifier

(ii) CE amplifier (iii) CC amplifier





| Transistor as C.E. amplifier | Transistor as C.B. amplifier |
|--|---|
| (i) Current gain (<i>a</i>) | (i) Current gain (β) |
| (a) $\alpha_{ac} = \frac{\text{Small change in collector current } (\Delta i_c)}{\text{Small change in collector current } (\Delta i_e)};$ | (a) $\beta_{ac} = \left(\frac{\Delta i_c}{\Delta i_b}\right) V_{CE} = \text{constant}$ |
| V_B (constant) | |
| (b) $\alpha_{dc}(\text{or }\alpha) = \frac{\text{Collector current}(i_c)}{\text{Emitter current}(i_e)}$ | (b) $\beta_{dc} = \frac{i_c}{i_b}$ |
| value of a_{dc} lies between 0.95 to 0.99 | valve of eta_{ac} lies between 15 and 20 |
| (ii) Voltage gain | (ii) Voltage gain |
| $A_{\nu} = \frac{\text{Change in output voltage}(\Delta V_o)}{\text{Change in input voltage}(\Delta V_i)}$ | $A_v = \frac{\Delta V_o}{\Delta V_i} = \beta_{ac} \times \text{Resistance gain}$ |
| \Rightarrow $A_v = \alpha_{ac} \times \text{Resistance gain}$ | |
| (iii) Power gain = $\frac{\text{Change in output power}(\Delta P_o)}{\text{Change in input power}(\Delta P_c)}$ | (iii) Power gain = $\frac{\Delta P_o}{\Delta P_i} = \beta_{ac}^2 \times \text{Resistance gain}$ |
| \Rightarrow Power gain = α_{ac}^2 × Resistance gain | Note: D Trans conductance (gm) : The |
| | ratio of the change in collector current to the change in emitter base voltage is called |
| | trans conductance. <i>i.e.</i> $g_m = \frac{\Delta i_c}{\Delta V_{EB}}$. |
| | Also $g_m = \frac{A_V}{R_L}$; R_L = Load resistance |

(4) Parameters of CE/CB amplifiers

(5) Relation between α and β :

$$\beta = \frac{\alpha}{1-\alpha}$$
 or $\alpha = \frac{\beta}{1+\beta}$

(6) Comparison between CB, CE and CC amplifier

| S.No. | Characteristic | Amplifier | | |
|-------|--|----------------------------------|---------------------------|----------------------------|
| | | СВ | CE | СС |
| (i) | Input resistance (R_i) | \approx 50 to 200 Ω low | ≈ 1 to 2 $k\Omega$ medium | ≈ 150 – 800 $k\Omega$ high |
| (ii) | Output resistance (R _o) | ≈ 1 – 2 $k\Omega$ high | ≈ 50 <i>k</i> Ω medium | $\approx k\Omega$ low |
| (iii) | Current gain | 0.8 - 0.9 low | 20 - 200 high | 20 – 200 high |

| (iv) | Voltage gain | Medium | High | Low |
|-------|--|---------|-------|---------|
| (v) | Power gain | Medium | High | Low |
| (vi) | Phase difference between input and output voltages | Zero | 180° | Zero |
| (vii) | Used as amplifier for | current | Power | Voltage |

Example

Example: 1What is the coordination number of sodium ions in the case of sodium chloride structure[CBSE 198;
(a) 6(a) 6(b) 8(c) 4(d) 12Solution : (a)In NaCl crystal Na⁺ ion is surrounded by $6Cl^-$ ion, therefore coordination number of Na⁺ is6.

Example: 2 A *Ge* specimen is doped with *Al*. The concentration of acceptor atoms is $\sim 10^{21} atoms/m^3$. Given that the intrinsic concentration of electron hole pairs is $\sim 10^{19} / m^3$, the concentration of electrons in the specimen is

[AIIMS 2004]

(a)
$$10^{17} / m^3$$
 (b) $10^{15} / m^3$ (c) $10^4 / m^3$ (d) $10^2 / m^3$

Solution: (a) $n_i^2 = n_h n_e \implies (10^{19})^2 = 10^{21} \times n_e \implies n_e = 10^{17} / m^3$.

Example: 3 A silicon specimen is made into a *P*-type semi-conductor by doping, on an average, one Indium atom per 5×10^7 silicon atoms. If the number density of atoms in the silicon specimen is 5×10^{28} atoms/m³, then the number of acceptor atoms in silicon will be

(a)
$$2.5 \times 10^{30}$$
 atoms/cm³ (b) 1.0×10^{13} atoms/cm³ (c) 1.0×10^{15} atoms/cm³ (d) 2.5×10^{36} atoms/cm³

Solution : (c) Number density of atoms in silicon specimen = $5 \times 10^{28} atom/m^3 = 5 \times 10^{22} atom/cm^3$ Since one atom of indium is doped in 5×10^7 *Si* atom. So number of indium atoms doped per cm^{-3} of silicon.

$$n = \frac{5 \times 10^{22}}{5 \times 10^{7}} = 1 \times 10^{15} atom / cm^{3}.$$

Example: 4 A *P*-type semiconductor has acceptor levels 57 meV above the valence band. The maximum wavelength of light required to create a hole is (Planck's constant $h = 6.6 \times 10^{-34}$ J-s)

- Solution : (c) $E = \frac{hc}{\lambda} \implies \lambda = \frac{hc}{E} = \frac{6.6 \times 10^{-34} \times 3 \times 10^{8}}{57 \times 10^{-3} \times 1.6 \times 10^{-19}} = 217100 \text{ Å}.$
- **Example: 5** A potential barrier of 0.50V exists across a *P-N* junction. If the depletion region is $5.0 \times 10^{-7} m$ wide, the intensity of the electric field in this region is

(a)
$$1.0 \times 10^6 V/m$$
 (b) $1.0 \times 10^5 V/m$ (c) $2.0 \times 10^5 V$

$$2.0 \times 10^5 V/m$$
 (d) $2.0 \times 10^6 V/m$

~~~

10 Ω

A B

Solution : (a)  $E = \frac{V}{d} = \frac{0.50}{5 \times 10^{-7}} = 1 \times 10^6 V/m.$ 

**Example: 6** A 2*V* battery is connected across the points *A* and *B* as shown in the figure given below. Assuming that the resistance of each diode is zero in forward bias and infinity in reverse bias, the current supplied by the battery when it  $10 \Omega$  ted to *A* is

| (a) | 0.2 | Α  |
|-----|-----|----|
| (u) | 0.2 | 11 |

- (b) 0.4 A
- (c) Zero
- (d) 0.1 A
- Solution : (a) Since diode in upper branch is forward biased and in lower branch is reversed biased. So current through circuit  $i = \frac{V}{R + r_d}$ ; here  $r_d$  = diode resistance in forward biasing = 0

So 
$$i = \frac{V}{R} = \frac{2}{10} = 0.2A$$
.

*Example:* 7 Current in the circuit will be

| (a) $\frac{5}{40}A$ | 20 |
|---------------------|----|
| (b) $\frac{5}{50}A$ | 30 |
| (c) $\frac{5}{10}A$ |    |
| (d) $\frac{5}{20}A$ |    |

Solution : (b) The diode in lower branch is forward biased and diode in upper branch is reverse biased

$$. \quad i = \frac{5}{20 + 30} = \frac{5}{50} A$$

*Example:* 8 Find the magnitude of current in the following circuit

(a) 0

(b) 1 amp

- (c) 0.1 amp
- (d) 0.2 amp

- $-4V 3\Omega -1$
- Solution : (a) Diode is reverse biased. Therefore no current will flow through the circuit.
- **Example: 9** The diode used in the circuit shown in the figure has a constant voltage drop of 0.5 V at all currents and a maximum power rating of 100 *milliwatts*. What should be the value of the resistor *R*, connected in series with the diode R to 5 V nt

(a) 1.5 Ω



(b) 5 Ω
(c) 6.67 Ω
(d) 200 Ω

- Solution : (b) The current through circuit  $i = \frac{P}{V} = \frac{100 \times 10^{-3}}{0.5} = 0.2A$ 
  - $\therefore$  voltage drop across resistance = 1.5 0.5 = 1 V  $\Rightarrow R = \frac{1}{0.2} = 5 \Omega$
- **Example: 10** For a transistor amplifier in common emitter configuration for load impedance of 1  $k\Omega$  ( $h_{fe}$  = 50 and  $h_{oe}$  = 25) the current gain is
  - (a) -5.2 (b) -15.7 (c) -24.8 (d) -48.78
- Solution : (d) In common emitter configuration current gain  $A_i = \frac{-h_{fe}}{1 + h_{oe}R_L} = \frac{-50}{1 + 25 \times 10^{-6} \times 10^3} = -48.78.$
- **Example: 11** In the following common emitter configuration an *NPN* transistor with current gain  $\beta$  = 100 is used. The output voltage of the amplifier will be
  - (a) 10 *mV*
  - (b) 0.1 V
  - (c) 1.0 V
  - (d) 10 V



Solution : (c) Voltage gain  $= \frac{\text{Output voltage}}{\text{Input voltage}}$ 

 $\Rightarrow$  V<sub>out</sub> = V<sub>in</sub> × Voltage gain

$$\Rightarrow V_{out} = V_{in} \times \text{Current gain} \times \text{Resistance gain} = V_{in} \times \beta \times \frac{R_L}{R_{BE}} = 10^{-3} \times 100 \times \frac{10}{1} = 1V.$$

- **Example: 12**While a collector to emitter voltage is constant in a transistor, the collector current<br/>changes by 8.2 mA when the emitter current changes by 8.3 mA. The value of forward<br/>current ratio  $h_{fe}$  is[KCET 2002]
- (a) 82 (b) 83 (c) 8.2 (d) 8.3 Solution : (a)  $h_{fe} = \left(\frac{\Delta i_c}{\Delta i_b}\right)_{V_{ce}} = \frac{8.2}{8.3 - 8.2} = 82$
- **Example: 13**The transfer ratio of a transistor is 50. The input resistance of the transistor when used in<br/>the common-emitter configuration is 1  $K\Omega$ . The peak value for an ac input voltage of 0.01 V<br/>peak is(a) 100  $\mu A$ (b) 0.01 mA(c) 0.25 mA(d) 500  $\mu A$
- Solution : (d)  $i_c = \beta i_b = \beta \times \frac{V_i}{R_i} = 50 \times \frac{0.01}{1000} = 500 \times 10^{-6} A = 500 \ \mu A$
- *Example*: 14 In a common base amplifier circuit, calculate the change in base current if that in the emitter current is 2 *mA* and  $\alpha$  = 0.98
  - (a) 0.04 mA (b) 1.96 mA (c) 0.98 mA (d) 2 mA

Solution : (a)  $\Delta i_c = \alpha \Delta i_e = 0.98 \times 2 = 196 \text{ mA}$ 

 $\therefore \ \Delta i_b = \Delta i_e - \Delta i_c = 2 - 1.96 = 0.04 \ mA$  .